SCBS146D - MAY 1992 - REVISED NOVEMBER 1996

 State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power 	SN54LVT16500 WD PACKAGE SN74LVT16500 DGG OR DL PACKAGE (TOP VIEW)
Dissipation	
 Members of the Texas Instruments Widebus™ Family 	LEAB 2 55 CLKAB A1 3 54 B1
 Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC}) 	GND [4 53] GND A2 [5 52] B2
 Support Unregulated Battery Operation Down to 2.7 V 	A3 [6 51] B3 V _{CC} [7 50] V _{CC}
 UBT[™] (Universal Bus Transceiver) 	A4 [8 49] B4
Combines D-Type Latches and D-Type	A5 0 9 48 B5
Flip-Flops for Operation in Transparent,	A6 🛛 10 47 🕽 B6
Latched, or Clocked Mode	GND [] 11 46 [] GND
 Typical V_{OLP} (Output Ground Bounce) 	A7 12 45 B7
< 0.8 V at V _{CC} = 3.3 V, T _A = 25°C	A8 🛛 13 44 🗍 B8 A9 🗍 14 43 🗍 B9
 ESD Protection Exceeds 2000 V Per 	A10 15 42 B10
MIL-STD-883, Method 3015; Exceeds 200 V	A11 16 41 B11
Using Machine Model	A12 17 40 B12
(C = 200 pF, R = 0)	GND 🛛 18 39 🗍 GND
 Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17 	A13 🛛 19 🛛 38 🗋 B13
	A14 20 37 B14
 Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown 	
Resistors	V _{CC} [22 35] V _{CC} A16 [23 34] B16
Support Live Insertion	A10 23 34 B10 A17 24 33 B17
••	GND 25 32 GND
 Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise 	A18 26 31 B18
 Flow-Through Architecture Optimizes 	
PCB Layout	LEBA [28 29] GND

 Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'LVT16500 are 18-bit universal bus transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A-bus data is stored in the latch/flip-flop on the high-to-low transition of CLKAB. Output-enable OEAB is active high. When OEAB is high, the B-port outputs are active. When OEAB is low, the B-port outputs are in the high-impedance state.



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description (continued)

Data flow for B to A is similar to that of A to B but uses OEBA, LEBA, and CLKBA. The output enables are complementary (OEAB is active high and OEBA is active low).

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN74LVT16500 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the I/O pin count and functionality of standard small-outline packages in the same printed circuit board area.

The SN54LVT16500 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74LVT16500 is characterized for operation from -40°C to 85°C.

	FUNCTION TABLE									
	INPUTS									
OEAB	LEAB	CLKAB	Α	В						
L	Х	Х	Х	Z						
н	Н	Х	L	L						
н	Н	Х	Н	н						
н	L	\downarrow	L	L						
н	L	\downarrow	Н	н						
н	L	Н	Х	в ₀ ‡ во§						
н	L	L	Х	в ₀ §						

FUNCTION TABLET

[†]A-to-B data flow is shown: B-to-A flow is similar but uses OEBA, LEBA, and CLKBA.

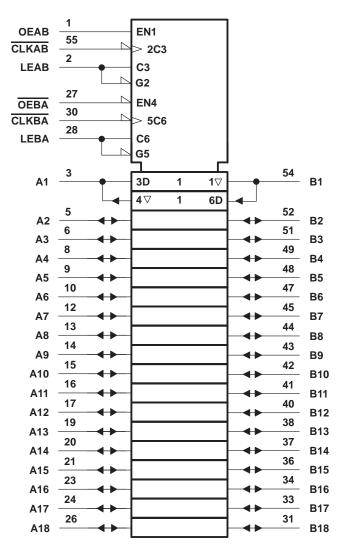
[‡]Output level before the indicated steady-state input conditions were established

§ Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low



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logic symbol[†]

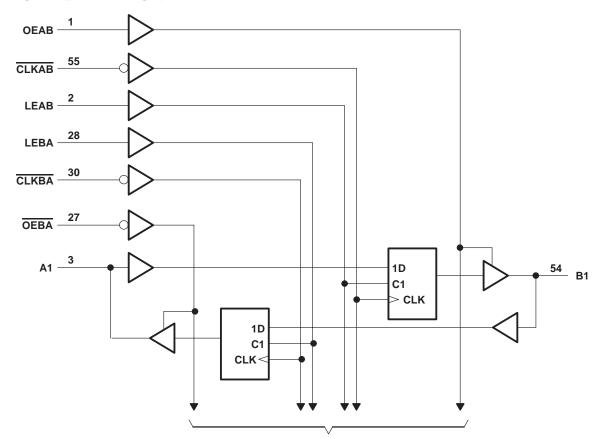


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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logic diagram (positive logic)



To 17 Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, VO (see Note 1)	. -0.5 V to 7 V
Current into any output in the low state, IO: SN54LVT16500	96 mA
SN74LVT16500	128 mA
Current into any output in the high state, I _O (see Note 2): SN54LVT16500	48 mA
SN74LVT16500	64 mA
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3): DGG package	
DL package	1.4 W
Storage temperature range, T _{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. This current flows only when the output is in the high state and $V_O > V_{CC}$.

3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*.



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recommended operating conditions (see Note 4)

			SN54LV	'T16500	SN74LV	T16500	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage		2	ĬEI,	2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage			2 5.5		5.5	V
ЮН	High-level output current		S.	-24		-32	mA
IOL	Low-level output current		0	48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled	40	10		10	ns/V
ТА	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		SN	54LVT16	500	SN7	4LVT16	500	LINUT				
PARAMETER		ST CONDITIONS		MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNIT		
VIK	V _{CC} = 2.7 V,	lj = -18 mA				-1.2			-1.2	V		
	V _{CC} = 2.7 V to 3.6 V,	I _{OH} = -100 μA	V _{CC} -0	.2		V _{CC} –0	.2					
Varia	V _{CC} = 2.7 V,	I _{OH} =8 mA		2.4			2.4			V		
VOH	V _{CC} = 3 V	I _{OH} = -24 mA	2						v			
	VCC = 3 V	I _{OH} = -32 mA					2					
	V _{CC} = 2.7 V	I _{OL} = 100 μA				0.2			0.2			
	VCC = 2.7 V	I _{OL} = 24 mA				0.5			0.5			
VOL		I _{OL} = 16 mA			0.4			0.4	V			
٧OL	$V_{CC} = 3 V$	I _{OL} = 32 mA			0.5			0.5	v			
		I _{OL} = 48 mA			<u>0.55</u>							
		I _{OL} = 64 mA			4			0.55				
	V _{CC} = 3.6 V,	$V_I = V_{CC} \text{ or } GND$	Control		24	±1			±1			
	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V	inputs		K	10			10			
li 🗌		V _I = 5.5 V			5	20			20	μΑ		
	V _{CC} = 3.6 V	$V_I = V_{CC}$	A or B ports‡	ò	2	5			5			
		$V_{I} = 0$		Q		-10			-10			
I _{off}	$V_{CC} = 0,$	V_{I} or $V_{O} = 0$ to 4.5	V			±100			±100	μΑ		
	$V_{CC} = 3 V$	V _I = 0.8 V	A or B ports	75			75			μA		
l(hold)	100-01	V _I = 2 V		-75			-75			μπ		
IOZH	V _{CC} = 3.6 V,	V _O = 3 V				1			1	μΑ		
IOZL	V _{CC} = 3.6 V,	V _O = 0.5 V				-1			-1	μΑ		
			Outputs high			0.12			0.12			
ICC	$V_{CC} = 3.6 V,$	$I_{O} = 0,$	Outputs low			5			5	mA		
'CC	$V_{I} = V_{CC} \text{ or } GND$		Outputs disabled	0.12			0.12					
∆ICC§	$V_{CC} = 3 V \text{ to } 3.6 V,$ Other inputs at V_{CC} or G					0.2			0.2	mA		
Ci	V _I = 3 V or 0			3.5			3.5		pF			
C _{io}	V _O = 3 V or 0				12			12		pF		

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. [‡] Unused pins at V_{CC} or GND

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			SN54LVT16500									
			V _{CC} = ± 0.3		V _{CC} =	2.7 V	V _{CC} = ± 0.3		V _{CC} =	2.7 V	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
fclock	Clock frequency		0	150	0	125	0	150	0	125	MHz	
tw Pulse duration	LE high	3.3		3.3		3.3		3.3		ns		
١w	t _w Pulse duration	CLK high or low	3.3		3.3		3.3		3.3		115	
		A before CLKAB↓	1.8		21.1		1.8		1.1			
	O a trum time a	B before CLKBA↓	1.9	1	1.2		1.9		1.2			
t _{su}	Setup time	A or B before LE \downarrow , CLK high	2.2	5	1.3		2.2		1.3		ns	
		A or B before LE \downarrow , CLK low	2.7	0	1.9		2.7		1.9			
4.	Hold time	A or B after $\overline{CLK}\downarrow$	1.2	Q	1.2		1.2		1.2			
th		A or B after LE \downarrow	0.9		1.1		0.9		1.1		ns	

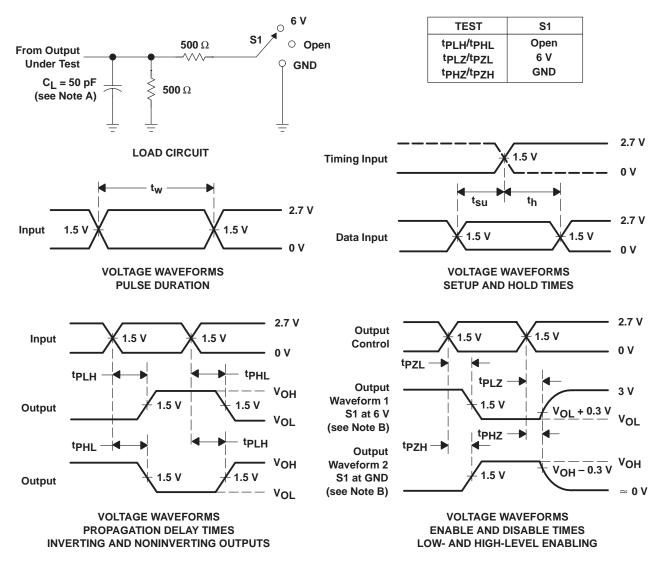
switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

			SN54LVT16500				SN7	4LVT16	500				
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V			V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT	
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN	MAX		
fmax			150		125		150			125		MHz	
^t PLH	D or A	A or B	1.7	5.8		7	1.7	3	5.4		6.8	ns	
^t PHL	B or A	AUB	1.6	6	MJ,	7.8	1.6	3.2	5.9		7.7	115	
^t PLH	LEBA or LEAB	A or B	2.3	7.3	LEV.	8.9	2.3	4	7		8.5	200	
^t PHL	LEDA OI LEAD	AUB	2.7	8.2	40	9.8	2.7	4.3	7.9		9.7	9.7 ns	
^t PLH	CLKBA or	A or B	2	7.4	h	8.8	2	4.1	7		8.3	ns	
^t PHL	CLKAB	AUB	2.4	8.1		10	2.4	4.4	7.9		9.9	115	
^t PZH	OEBA or	A or B	1.2	5.2		6.1	1.2	3	5		5.9	ns	
^t PZL	OEAB	AUB	1.5	5.9		7	1.5	3	5.8		6.9	115	
^t PHZ	OEBA or	A or B	2.7	7.7		8.6	2.7	4.6	7.4		8.3	ns	
^t PLZ	OEAB	AUB	2.8	7.3		7.7	2.8	4.7	6.7		7.2	115	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}, \text{ T}_{A} = 25^{\circ}\text{C}.$



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
74LVT16500DGGRE4	NRND	TSSOP	DGG	56		TBD	Call TI	Call TI	
74LVT16500DGGRG4	NRND	TSSOP	DGG	56		TBD	Call TI	Call TI	
SN74LVT16500DGGR	OBSOLETE	TSSOP	DGG	56		TBD	Call TI	Call TI	
SN74LVT16500DL	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI	
SN74LVT16500DLR	NRND	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LVT16500DLRG4	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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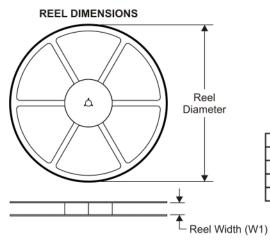
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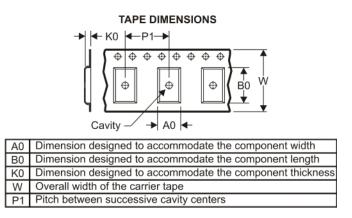
PACKAGE MATERIALS INFORMATION

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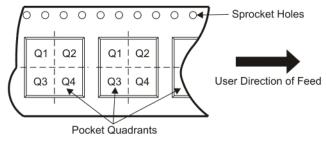
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



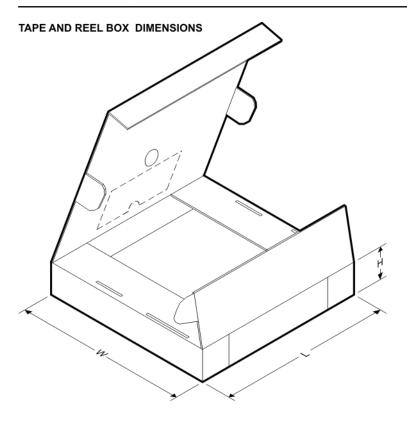
All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVT16500DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

29-Jul-2011



*All dimensions are nominal

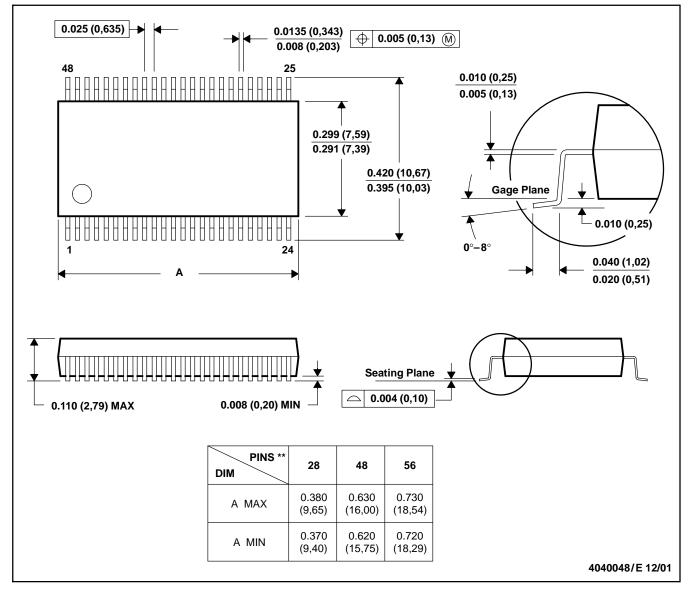
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVT16500DLR	SSOP	DL	56	1000	346.0	346.0	49.0

MECHANICAL DATA

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

PLASTIC SMALL-OUTLINE PACKAGE

DL (R-PDSO-G**) 48 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118



MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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